## I Claim:

1. A sensor for measuring heat flux in a solid body comprising:

a thin substrate of thermally conducting, electrically insulating material; a thin film thermopile deposited on a surface of said substrate with hot junctions near one end of said substrate and cold junctions near the other end of said substrate; a thin, flat plate of thermally conducting, electrically insulating material for covering the thermopile on said substrate; electrical connections on said thin film thermopile for measuring its voltage; and means for imbedding said substrate and said plate within said solid body.

2. The sensor of claim 1 in which said means for imbedding said substrate and said plate within said body comprise:

a threaded, slotted plug for holding said substrate and said flat plate together; and a threaded hole in said solid body.

3. The sensor of claim 1 in which said means for imbedding said substrate and said plate within said body comprise:

a cylindrical plug for holding said substrate and said flat plate together; and a hole in said solid body with diameter suitable for a press fit of said plug into said hole in said solid body.

- 4. The sensor of claim 1 in which said slot is formed in the side of said plug.
- 5. The sensor of claim 1 in which said slot is formed in the end of said plug.
- 6. The sensor of claim 1 in which said means for imbedding said substrate comprises a hole in said solid sol

h soe into said solid object.

- 7. The sensor of claim 1 in which the materials of said substrate and said flat plate have thermal properties closely matching those of said solid object.
  - 8. The sensor of claim 2 in which the materials of said substrate and said flat plate and said plug be dy have thermal properties closely matching those of said solid object.
    - 9. A method for measuring heat flux in a solid body consisting of:
  - depositing a thin film thermopile on A thin substrate of thermally conducting, electrically insulating material with hot junctions near one end of said substrate and cold junctions near the other end of said substrate;

covering said thin film thermopile on said substrate with a thin, flat plate of thermally conducting, electrically insulating material;

imbedding said substrate and said plate within said solid body; and

where measuring its potential
making electrical connections to said thermopile.

- 10. The method of claim 9 in which the materials of said substrate and said flat plate have thermal properties closely matching those of said solid objects
- 11. The method of claim 10 in which said substrate and said plate are imbedded by first enclosing them in a threaded plug whose thermal properties closely match those of said solid object and inserting said plug in a threaded hole in said solid body.

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